

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	222715	438/\$.ccls. 257/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM TDB
2	BRS	L2	4585	1 and (copper or Cu or metal) adj (interconnect? or via? or plug? or contact?)	USPAT; EPO; JPO; DERWENT; IBM TDB
3	BRS	L3	197	2 and seed adj layer	USPAT; EPO; JPO; DERWENT; IBM TDB
4	BRS	L4	151	3 and diffus\$3	USPAT; EPO; JPO; DERWENT; IBM TDB
5	BRS	L5	21	4 and implant\$5	USPAT; EPO; JPO; DERWENT; IBM TDB
6	BRS	L6	16	5 and dop\$4	USPAT; EPO; JPO; DERWENT; IBM TDB
7	BRS	L7	16	6 and (Al or Mg or Sn)	USPAT; EPO; JPO; DERWENT; IBM TDB
8	BRS	L8	4	7 and vacuum	USPAT; EPO; JPO; DERWENT; IBM TDB
9	BRS	L9	0	7 and (expos\$3 near (oxygen or nitrogen))	USPAT; EPO; JPO; DERWENT; IBM TDB
10	BRS	L10	3	(Marieb-Thomas-N or McGregor-Paul or Block-Carolyn or Jin-Shu).in.	USPAT; EPO; JPO; DERWENT; IBM TDB
11	BRS	L11	0	10 and (copper or Cu or metal) adj (interconnect? or via? or plug? or contact?)	USPAT; EPO; JPO; DERWENT; IBM TDB
12	BRS	L12	579	((copper or Cu or metal) adj (interconnect? or via? or plug? or contact?)).ti.	USPAT; EPO; JPO; DERWENT; IBM TDB
13	BRS	L13	0	12 and doped adj seed	USPAT; EPO; JPO; DERWENT; IBM TDB
14	BRS	L14	25	12 and seed	USPAT; EPO; JPO; DERWENT; IBM TDB
15	BRS	L15	16	14 and cap\$4	USPAT; EPO; JPO; DERWENT; IBM TDB
16	BRS	L16	3	15 and oxygen	USPAT; EPO; JPO; DERWENT; IBM TDB
17	BRS	L17	10882	(copper or Cu or metal) adj (interconnect? or via? or plug? or contact?)	USPAT; EPO; JPO; DERWENT; IBM TDB
18	BRS	L18	5676	17 and (diffus\$3 or implant\$3 or dop\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB
19	BRS	L19	1561	17 and (diffus\$3 and implant\$3 and dop\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB

	Type	L #	Hits	Search Text	DBs
20	BRS	L20	869	19 and anneal\$3	USPAT; EPO; JPO; DERWENT; IBM TDB
21	BRS	L21	4609	20 adn electronmigration	USPAT; EPO; JPO; DERWENT; IBM TDB
22	BRS	L22	37	20 and electromigration	USPAT; EPO; JPO; DERWENT; IBM TDB
23	BRS	L23	37	22 and (Al or Mg or Sn)	USPAT; EPO; JPO; DERWENT; IBM TDB
24	BRS	L24	6	23 and vacuum	USPAT; EPO; JPO; DERWENT; IBM TDB